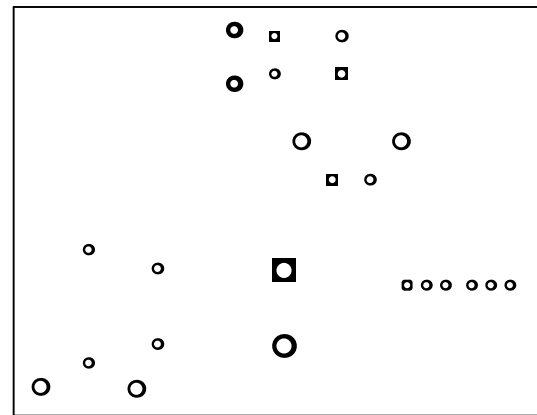
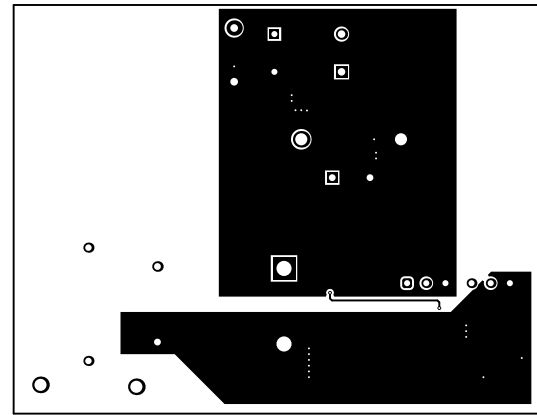


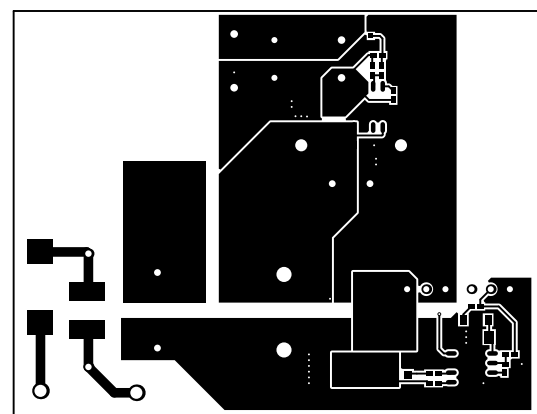
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 5/23/2017 10:35:41 AM	TEXAS INSTRUMENTS	



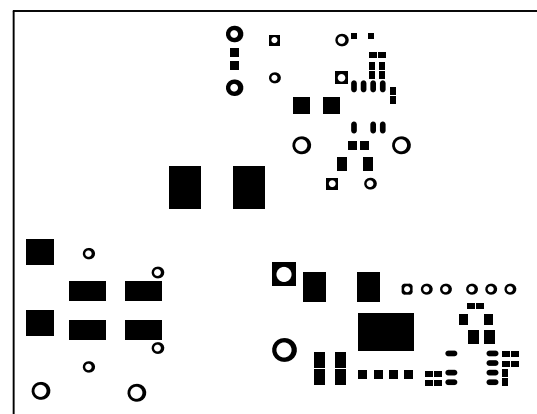
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 5/23/2017 10:35:42 AM	TEXAS INSTRUMENTS	



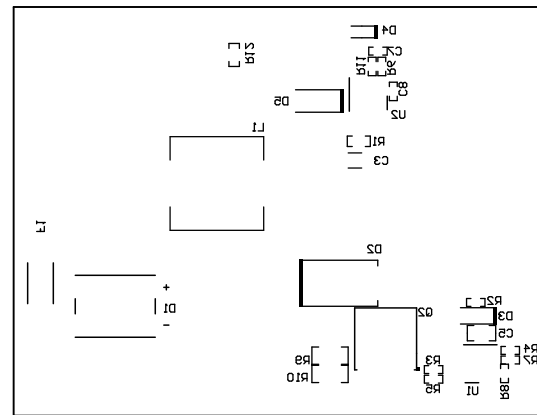
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 5/23/2017 10:35:42 AM	TEXAS INSTRUMENTS	



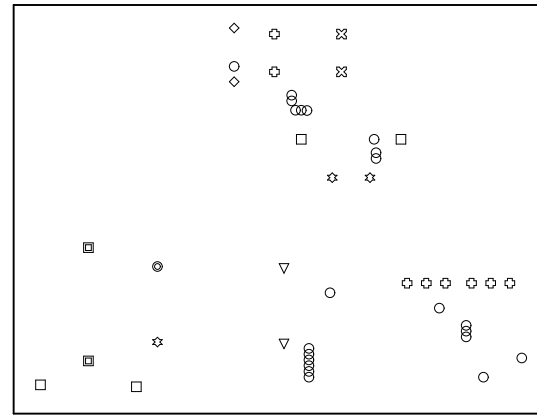
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 5/23/2017 10:35:43 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/23/2017 10:35:43 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 5/23/2017 10:35:44 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	22	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	8	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
■	2	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
☆	3	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
●	1	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	+/-1.97mil
⊗	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
◇	2	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
	46 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 5/23/2017 10:35:44 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20686	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 5/23/2017 10:35:45 AM	TEXAS INSTRUMENTS	

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